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1. ~~A display comprising:~~
a plurality of substrates;
a plurality of display elements formed on each
substrate;
an integrated circuit block attached to each
substrate and coupled to at least one of said display
elements; and
an integrator to couple said substrates to form a
~~tilde display.~~

2. The display of claim 1 wherein said display
element is a light emitting diode.

3. The display of claim 2 wherein said element is an
organic light emitting diode.

4. The display of claim 1 wherein said integrated
circuit block is a complementary metal oxide semiconductor
integrated circuit.

5. The display of claim 1 wherein said substrate
includes a recess to receive said block.

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~~6. The display of claim 5 wherein said block and
said substrate and complementarily shaped.~~

1 6 ~~7~~. The display of claim 1 wherein said block is a
2 driver circuit for said display element.

1 7 ~~8~~. The display of claim ⁶~~7~~ wherein said block is
2 located between a plurality of display elements.

1 8 ~~9~~. The display of claim 1 wherein said block is
2 metallized with said substrate.

1 9 ~~10~~. The display of claim 1 including a ceramic back
2 plane and a front plane including said block.

1 10 ~~11~~. The display of claim 1 wherein said block is
2 formed of a silicon substrate and said substrate is formed
3 of glass.

1 12. A display comprising:
2 a back plane;
3 an optical integrator; and
4 a front plane between said back plane and said
5 optical integrator, said front plane including a plurality
6 of emissive display elements formed on said front plane and
7 an integrated circuit block secured in said front plane and
8 including driver circuits coupled to said display elements
9 and to said back plane.

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1 13. The display of claim 12 wherein said display
2 elements are light emitting diodes.

1 14. The display of claim 13 wherein said elements are
2 organic light emitting diodes.

1 15. The display of claim 12 wherein said block is
2 formed of a metal oxide semiconductor integrated circuit
3 and said front plane is formed of glass.

1 16. The display of claim 12 wherein said block is
2 deposited in a recess formed in said front plane.

1 17. The display of claim 12 wherein said driver
2 circuit drives a plurality of adjacent display elements.

1 18. A method comprising:
2 forming a plurality of light emitting display
3 elements on a module;
4 forming recesses in said module to receive
5 integrated circuit nanoblocks;
6 depositing said nanoblocks in said recesses;
7 electrically coupling said nanoblocks to said
8 display elements; and
9 connecting a plurality of modules to form a tiled
10 display.

1 19. The method of claim 18 including etching a recess
2 in said module to receive said integrated circuit
3 nanoblock.

1 20. The method of claim 18 including forming a
2 plurality of nanoblocks by forming a sacrificial layer on a
3 silicon substrate, etching said substrate and then finally
4 etching said sacrificial layer.

1 21. The method of claim 18 including coupling said
2 nanoblocks to circuits behind said light emitting display.

1 22. The method of claim 18 including coupling said
2 nanoblocks to said circuits through bond pads on said
3 nanoblocks.

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